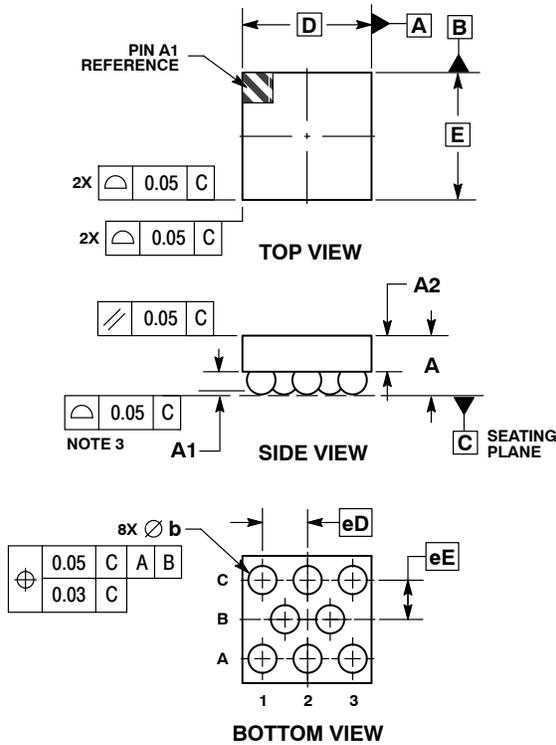




SCALE 4:1

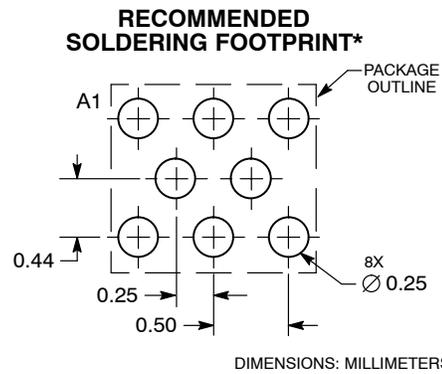
**WLCSP8, 1.43x1.41**  
**CASE 567BE**  
**ISSUE O**

DATE 26 JUL 2010



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	0.56	0.65
A1	0.21	0.27
A2	0.40 REF	
b	0.29	0.35
D	1.43 BSC	
E	1.41 BSC	
eD	0.50 BSC	
eE	0.435 BSC	



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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<b>DESCRIPTION:</b>	<b>WLCSP8, 1.43X1.41</b>	<b>PAGE 1 OF 1</b>

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